

Innovating Energy Technology

http://www.fujielectric.com/products/semiconductor/ **FUJI POWER MOSFET**

Super J MOS[®] S2 series

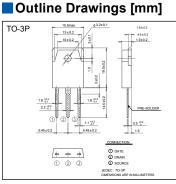
N-Channel enhancement mode power MOSFET

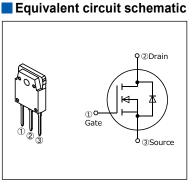
Features

Pb-free lead terminal **RoHS** compliant uses Halogen-free molding compound

Applications

For switching





Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

Parameter	Symbol	Characteristics	Unit	Remarks
Drain Source Voltage	VDS	600	V	
Drain-Source Voltage	V _{DSX}	600	V	V _{GS} =-30V
Continuous Drain Current	,	13	А	Tc=25°C Note*1,2
Continuous Drain Current	I _D	8.2	А	Tc=100°C Note*1,2
Pulsed Drain Current	I _{DP}	41.6	А	Note *2
Gate-Source Voltage	Vgs	±30	V	
Non-Repetitive Maximum Avalanche Current	las	1.5	А	Note *3
Non-Repetitive Maximum Avalanche Energy	Eas	468	mJ	Note *4
Maximum Drain-Source dV/dt	d <i>V</i> ⊳s/dt	50	V/ns	V _{DS} ≤ 600V
Continuous		13	А	Tc=25°C Note*1,2
Diode Forward Current	Isd	8.2	А	Tc=100°C Note*1,2
Pulsed Diode Forward Current	ISDP	41.6	А	Note *2
Peak Diode Recovery dV/dt	dV/dt	15	V/ns	Note *5
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note *6
Maximum Dawar Disaination	PD	2.50	W	<i>T</i> ₂=25°C
Maximum Power Dissipation	F D	65	vv	<i>T</i> c=25°C
Operating and Storage Temperature renge	Tch	150	°C	
Operating and Storage Temperature range	T _{stg}	-55 to +150	°C	

Note *1 : Maximum duty cycle D=0.65

Note *1: Imited by maximum channel temperature. Note *3: Imited by maximum channel temperature. Note *3: T_{ch}≤150°C, See Fig.1 and Fig.2 Note *4: Starting T_{ch}=25°C, I_{As}=0.9A, L=1.06H, V_{DD}=60V, R_G=50Ω, See Fig.1 and Fig.2 E_{As} limited by maximum channel temperature and avalanche current. Note *5: I_{SD}≤10.4A, -di/dt≤100A/μs, V_{DS} peak≤600V, T_{ch}≤150°C. Note *6: I_{SD}≤10.4A, dV/dt≤15V/ns, V_{DS} peak≤600V, T_{ch}≤150°C.

Electrical Characteristics at T_c=25°C (unless otherwise specified) Static Ratings

Parameter	Symbol	Conditions		Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I⊵=250µA		600	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} I₀=150µA		2.5	3.0	3.5	V
Zero Gate Voltage Drain Current	Ioss	V _{DS} =600V V _{GS} =0V	T _{ch} =25°C	-	-	25	-μA
		V _{DS} =480V V _{GS} =0V	<i>T</i> _{ch} =125°C	-	-	250	
Gate-Source Leakage Current	Igss	V _{DS} =0V V _{GS} =±30V		-	10	100	nA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V I _D =5.2A		-	0.248	0.280	Ω
Gate resistance	RG	f=1MHz, open drain		-	12.7	-	Ω

Dynamic Ratings

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Transconductance	g _{fs}	V _{DS} =25V I _D =5.2A	4.7	9.5	-	S
Input Capacitance	Ciss	V _{DS} =400V	-	790	-	
Output Capacitance	Coss	V _{GS} =0V	-	22	-	
Reverse Transfer Capacitance	Crss	f=250kHz	-	3.5	-	
Effective output capacitance, energy related (Note *7)	Co(er)	V _{DS} =0400V V _{GS} =0V	-	53	-	pF
Effective output capacitance, time related (Note *8)	Co(tr)	V₀s=0400V V₀s=0V I₀=constant	- 183	-		
	t _{d(on)}	V ₀₀ =400V, V _{GS} =10V /₀=5.2A, R _G =18Ω See Fig.3 and Fig.4	-	15	-	- ns
Turn-On Time	tr		-	28	-	
Turn-Off Time	t _{d(off)}		-	95	-	
	<i>t</i> r		-	21	-	
Total Gate Charge	QG		-	33	-	nC
Gate-Source Charge	Q _{GS}	V_{DD} =400V, V_{GS} =10V	-	11	-	
Gate-Drain Charge	QGD	_ /₀=10.4A See Fig.5	-	9	-	
Drain-Source crossover Charge	Qsw		-	7	-	1

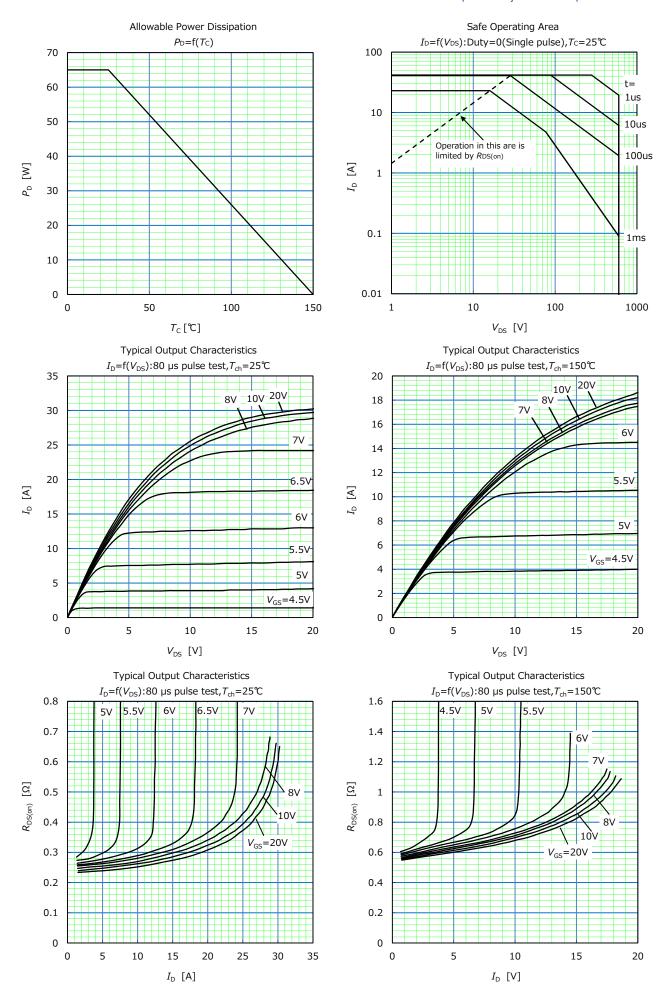
Note *7 : $C_{0(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 400V. Note *8 : $C_{0(er)}$ is a fixed capacitance that gives the same charging times as C_{oss} while V_{DS} is rising from 0 to 400V.

Reverse Diode

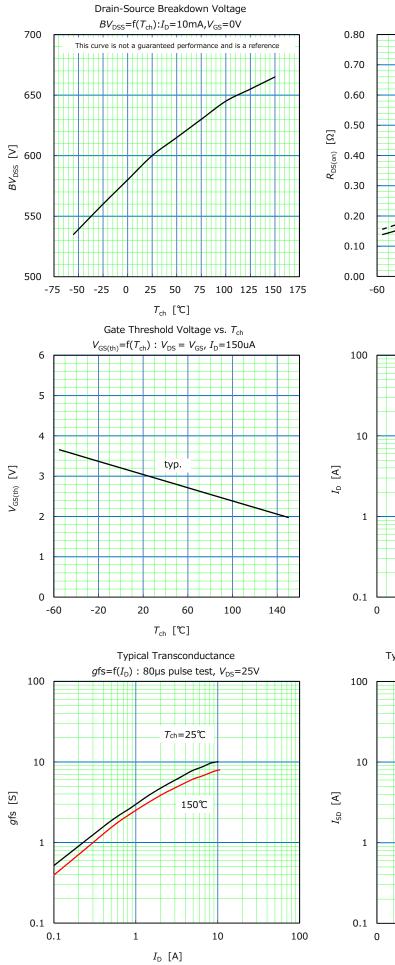
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Diode Forward On-Voltage	V _{SD}	/ _{SD} =10.4A, V _{GS} =0V 7 _{ch} =25°C	-	0.95	1.35	V
Reverse Recovery Time	trr	- V₀₀=400V, /₅₀=10.4A -di/dt=100A/µs T₅h=25°C See Fig.6 and Fig.7	-	290	-	ns
Reverse Recovery Charge	Qrr		-	2.9	-	μC
Peak Reverse Recovery Current	I rp		-	20.5	-	A

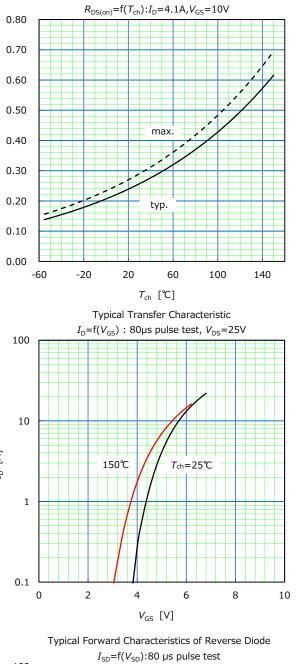
Thermal Resistance

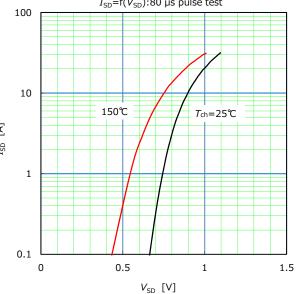
Parameter	Symbol	Min.	Тур.	Max.	Unit
Channel to Case	Rth(ch-c)	-	-	1.923	°C/W
Channel to Ambient	Rth(ch-a)	-	-	50	°C/W



Drain-Source On-state Resistance

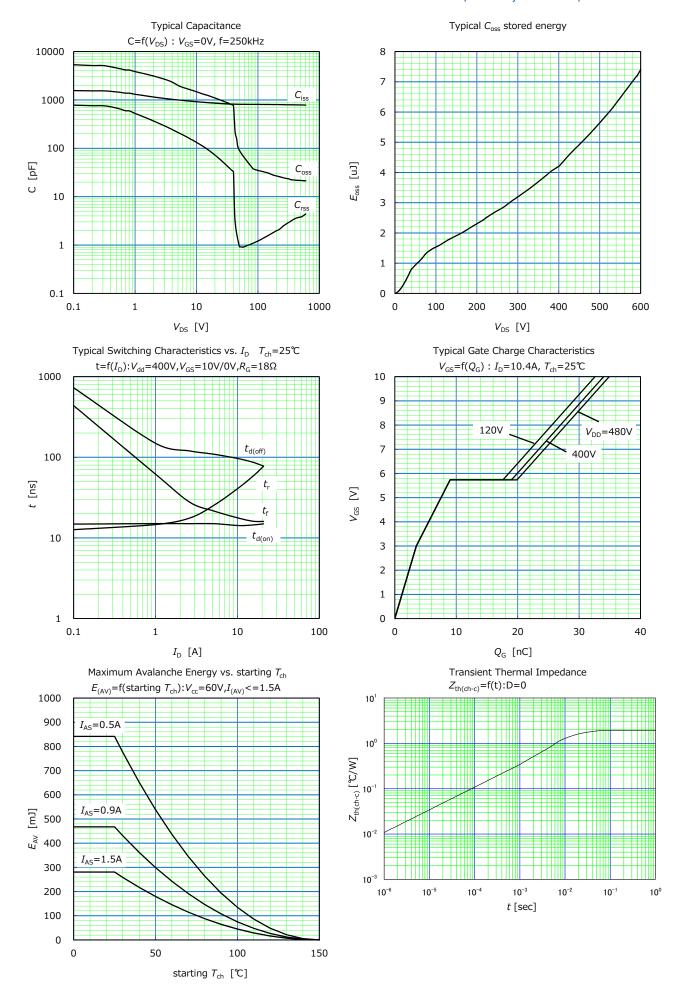






FMH60N280S2HF

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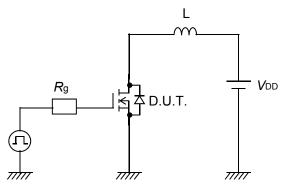


Fig.1 Avalanche Test circuit

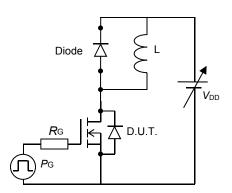


Fig.3 Switching Test circuit



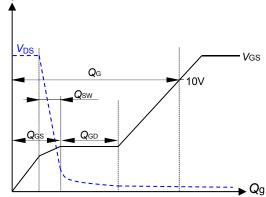
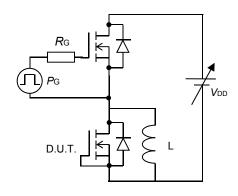
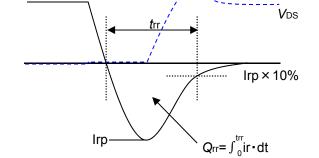


Fig.5 Operating waveform of Gate charge Test





. VDS peak

Fig.6 Reverse recovery Test circuit

Fig.7 Operating waveform of Reverse recovery Test

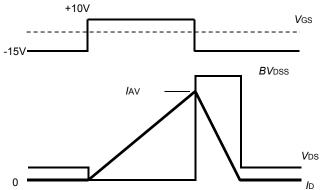


Fig.2 Operating waveforms of Avalanche Test

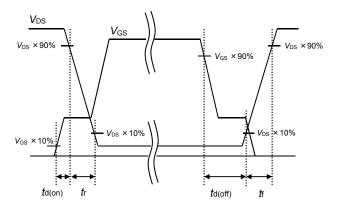


Fig.4 Operating waveform of Switching Test

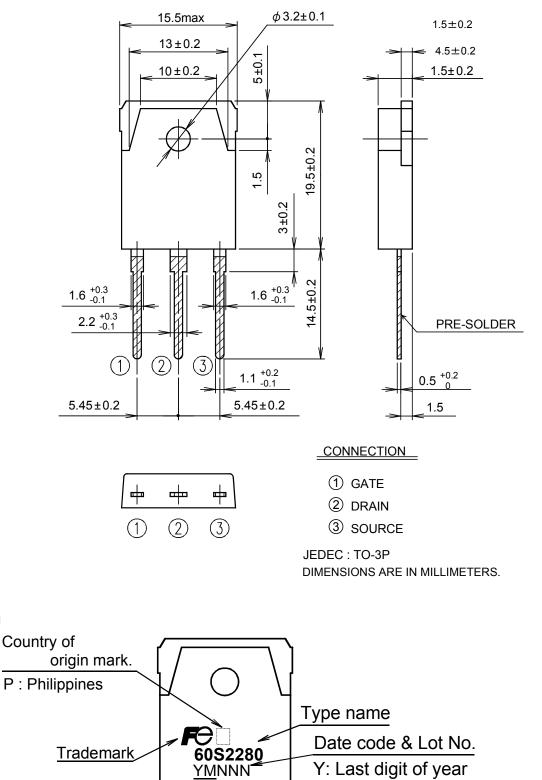
Isd

Marking

hf: Halogen-free mark

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Outview: TO-3P Package



NNN: Lot. serial number Under bar of date code : means lead-free mark

M: Month code 1~9 and O,N,D

* The font (font type,size) and the trademark-size might be actually different.

hf

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